

# TEM96E

# **Thermal Conductive RF Absorber Pad**

LiPOLY TEM96E is a thermally conductive absorber based upon soft magnetic materials dispersed in a polymeric resin. It has a thermal conductivity of 6.0 W/m\*K and dissipates electromagnetic radiation rapidly to mitigate against EMI issues.

# **■ FEATURES**

/ Thermal conductivity: 6.0 W/m\*K / Excellent absorption characteristics / Naturally tacky

#### / Reworkable

# **■ TYPICAL APPLICATION**

/ IC. CPU. MOS. LED. M/B. Heat sink / LCD-TV, Notebook PC, PC, Telecom device, Wireless hub / DDR II module, DVD applications, Hand-set applications / 5G base station & infrastructure / EV electric vehicle

#### **■ SPECIFICATIONS**

/ Sheet form / Die-cut parts

#### **■ FREQUENCY APPLICATION**

2.4 GHz Wi-Fi Router, Bluetooth 3.5 GHz 5G Mobile Networks

5.0 GHz Wi-Fi Router 6.0 GHz Wi-Fi Router

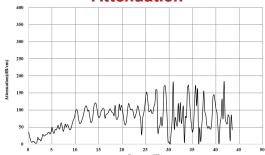
12~18 GHz Low Earth Orbit (LEO) System

28 GHz 5G Mobile Networks 39 GHz 5G Mobile Networks

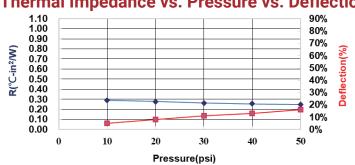
# **■ TYPICAL PROPERTIES**

PROPERTY	TEM96E	TEST METHOD	UNIT
Color	Dark Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	0.5~5.0	ASTM D374	mm
Density	3.8	ASTM D792	g/cm³
Hardness	75	ASTM D2240	Shore OO
TML	0.04	By LiPOLY	%
Water absorption	0.04	ASTM D570	%
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	5	ASTM D5470 modify	%
Deflection @20 psi	8	ASTM D5470 modify	%
Deflection @30 psi	11	ASTM D5470 modify	%
Deflection @40 psi	13	ASTM D5470 modify	%
Deflection @50 psi	16	ASTM D5470 modify	%
EMI Attenuation @1.0mm			
EMI attenuation@ 2.4 GHz	17.4	ASTM D4935 modify	dB/cm
EMI attenuation@ 3.5 GHz	28.6	ASTM D4935 modify	dB/cm
EMI attenuation@ 5.0 GHz	49.8	ASTM D4935 modify	dB/cm
EMI attenuation@ 6.0 GHz	44.8	ASTM D4935 modify	dB/cm
EMI attenuation@ 12 GHz	94.2	ASTM D4935 modify	dB/cm
EMI attenuation@ 18 GHz	91.1	ASTM D4935 modify	dB/cm
EMI attenuation@ 28 GHz	88.4	ASTM D4935 modify	dB/cm
EMI attenuation@ 39 GHz	41.5	ASTM D4935 modify	dB/cm
ELECTRICAL			'
Surface resistivity	>1011	ASTM D257	Ohm
Volume resistivity	>1010	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	6.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.288	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.278	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.264	ASTM D5470	°C-in²/W
Thermal impedance@40 psi	0.255	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.250	ASTM D5470	°C-in²/ W

#### **Attenuation**



# Thermal Impedance vs. Pressure vs. Deflection



Note: All specifications provided by LiPOLY are subject to change without notice. The test methods used by LiPOLY are based on the TIM Tester method and ASTM D5470 test method. These test methods are used as the definition standards for LiPOLY. Note: All specifications provided by LiPOLY are subject to change without notice. The test memods used by LiPOLY are based on the LIPOL steer memod and AST M USA/U test memod. These test memods are used as the definition standards for LiPOLY. Property values provided in this document are not for product specifications or guaranteed. This document need to sen of quarantee the performance and quality required for fire purchaser's specific purpose. The purchaser needs to evaluate and verify the safety before using the material. We strongly recommend the purchaser needs to evaluate and verify the safety before using the material. We strongly recommend the purchaser pre-test the product and verify the performance of the product under the purchaser's specific conditions. Liability and use of the product are the responsibility of the end user. LIPOLY makes no warrantly as to the suitability, merchantability, or non-infringement of any LiPOLY material or product for any specific or general uses. LiPOLY shall not be liable for incidental orconsequential damages of any kind. All LiPOLY products are sold in accordance with the LiPOLY Terms and Conditions in effect at the time of purchases and a cony of which will be furnished upon request. All rights reserved, including LiPOLY trademarks or registered trademarks of LiPOLY or its affiliates. Statements concerning possible or suggested uses made herein shall not be relied upon or be constructed as a guaranty of patent infringement. Copyright LiPOLY.